Plastic Packages for Integrated Circuits

Package Outline Drawing
L32.5x5H
32 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE (PUNCH QFN WITH WETABLE FLANK)
Rev 2, 1/16

SEE DETAIL "A"

TOP VIEW

SEE DETAIL "X"

SIDE VIEW

SEATING PLANE

DETAIL "X"

TYPICAL RECOMMENDED LAND PATTERN

NOTES:

1. Dimensions are in millimeters.
   Dimensions in ( ) for reference only.
3. Unless otherwise specified, tolerance: Decimal ± 0.05
4. Dimension applies to the plated terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
5. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
6. Reference document: JEDEC MO220